Lattice Semiconductor Corporation - LFSCM3GA115EP1-6FFN1152C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	28750
Number of Logic Elements/Cells	115000
Total RAM Bits	7987200
Number of I/O	660
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga115ep1-6ffn1152c

LatticeSC/M Family Data Sheet Introduction

January 2010 Data Sheet DS1004

Features

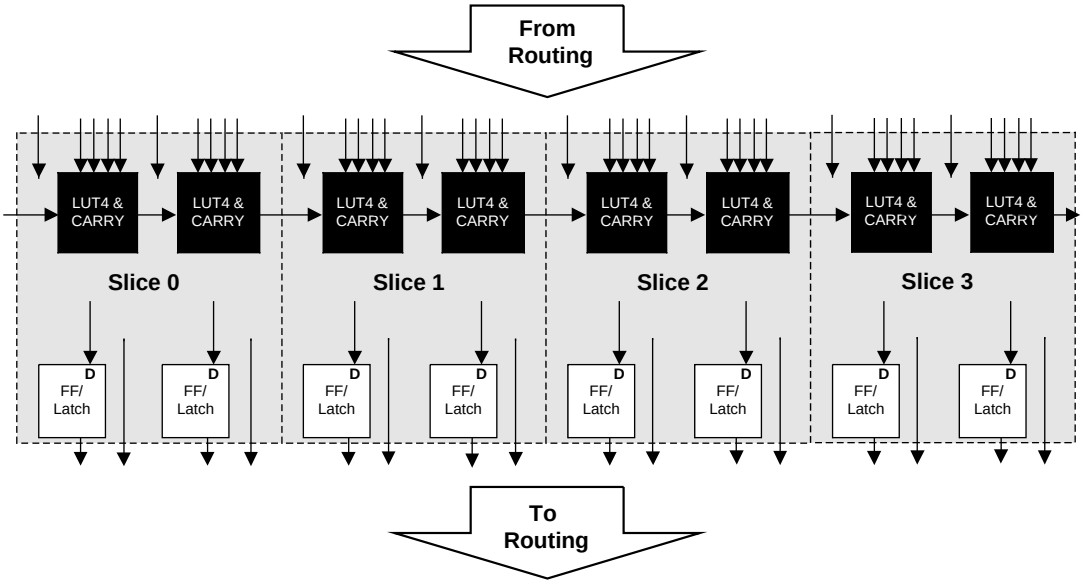
- **High Performance FPGA Fabric**
  - 15K to 115K four input Look-up Tables (LUT4s)
  - 139 to 942 I/Os
  - 700MHz global clock; 1GHz edge clocks
- **4 to 32 High Speed SERDES and flexiPCS™ (per Device)**
  - Performance ranging from 600Mbps to 3.8Gbps
  - Excellent Rx jitter tolerance (0.8UI at 3.125Gbps)
  - Low Tx jitter (0.25UI typical at 3.125Gbps)
  - Built-in Pre-emphasis and equalization
  - Low power (typically 105mW per channel)
  - Embedded Physical Coding Sublayer (PCS) provides pre-engineered implementation for the following standards:
    - GbE, XAUI, PCI Express, SONET, Serial RapidIO, 1G Fibre Channel, 2G Fibre Channel
- **2Gbps High Performance PURESPEED™ I/O**
  - Supports the following performance bandwidths
    - Differential I/O up to 2Gbps DDR (1GHz Clock)
    - Single-ended memory interfaces up to 800Mbps
  - 144 Tap programmable Input Delay (INDEL) block on every I/O dynamically aligns data to clock for robust performance
    - Dynamic bit Adaptive Input Logic (AIL) monitoring and control circuitry per pin that automatically ensures proper set-up and hold
    - Dynamic bus: uses control bus from DLL
    - Static per bit
  - Electrical standards supported:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2, LVTTL
    - SSTL 3/2/18 I, II; HSTL 18/15 I, II
    - PCI, PCI-X
    - LVDS, Mini-LVDS, Bus-LVDS, MLVDS, LVPECL, RSDS
  - Programmable On Die Termination (ODT)
    - Includes Thevenin Equivalent and low power V_{TT} termination options
- **Memory Intensive FPGA**
  - sysMEM™ embedded Block RAM
    - 1 to 7.8 Mbits memory
    - True Dual Port/Pseudo Dual Port/Single Port
    - Dedicated FIFO logic for all block RAM
    - 500MHz performance
  - Additional 240K to 1.8Mbits distributed RAM
- **sysCLOCK™ Network**
  - Eight analog PLLs per device
    - Frequency range from 15MHz to 1GHz
    - Spread spectrum support
  - 12 DLLs per device with direct control of I/O delay
    - Frequency range from 100MHz to 700MHz
  - Extensive clocking network
    - 700MHz primary and 325 MHz secondary clocks
    - 1GHz I/O-connected edge clocks
  - Precision Clock Divider
    - Phase matched x2 and x4 division of incoming clocks
  - Dynamic Clock Select (DCS)
    - Glitch free clock MUX
- **Masked Array for Cost Optimization (MACO™) Blocks**
  - On-chip structured ASIC Blocks provide pre-engineered IP for low power, low cost system level integration
- **High Performance System Bus**
  - Ties FPGA elements together with a standard bus framework
    - Connects to peripheral user interfaces for run-time dynamic configuration
- **System Level Support**
  - IEEE standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer
  - IEEE Standard 1532 in-system configuration
  - 1.2V and 1.0V operation
  - Onboard oscillator for initialization and general use
  - Embedded PowerPC microprocessor interface
  - Low cost wire-bond and high pin count flip-chip packaging
  - Low cost SPI Flash RAM configuration

PFU Blocks

The core of the LatticeSC devices consists of PFU blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram



Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to implement 5, 6, 7 and 8 Input LUTs (LUT5, LUT6, LUT7 and LUT8). There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SPR 16x2 DPR 16x2	ROM 16x2

Logic Mode

In this mode, the LUTs in each Slice are configured as combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices in the PFU.

Ripple Mode

Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Up counter 2-bit
- Down counter 2-bit
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Ripple Mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per slice basis to allow fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode

In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the Slice. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

ROM Mode

The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

Figure 2-13. DLL to PLL

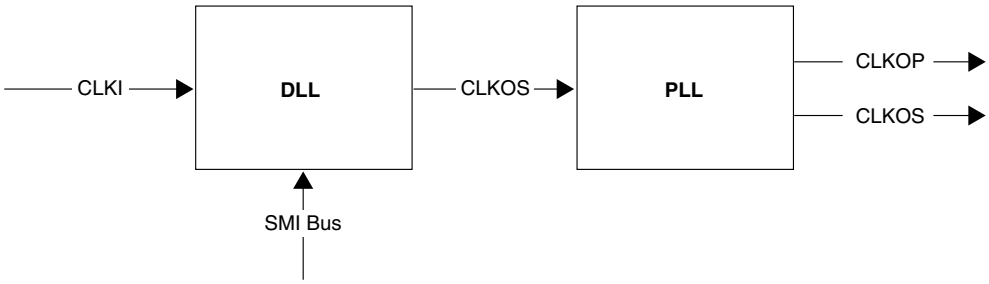


Figure 2-14 shows a shift of only CLKOP out in time.

Figure 2-14. PLL to DLL

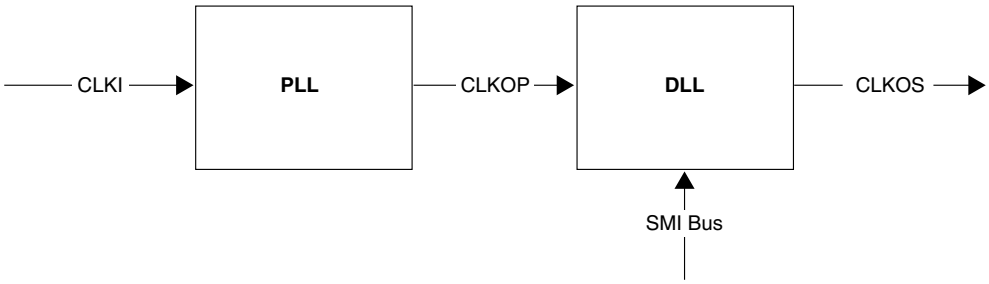
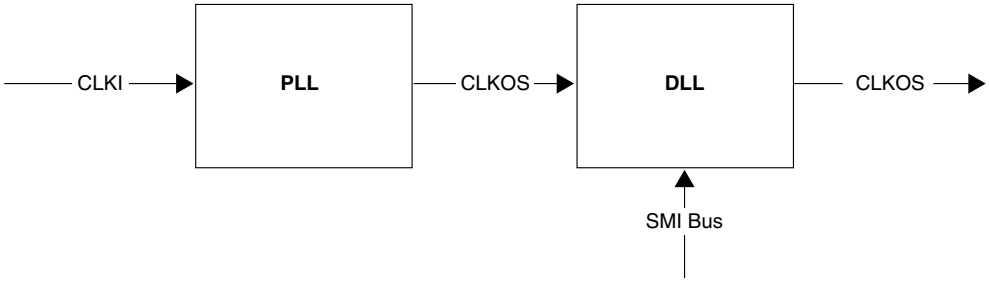


Figure 2-15 shows a shift of only CLKOS out in time.

Figure 2-15. PLL to DLL

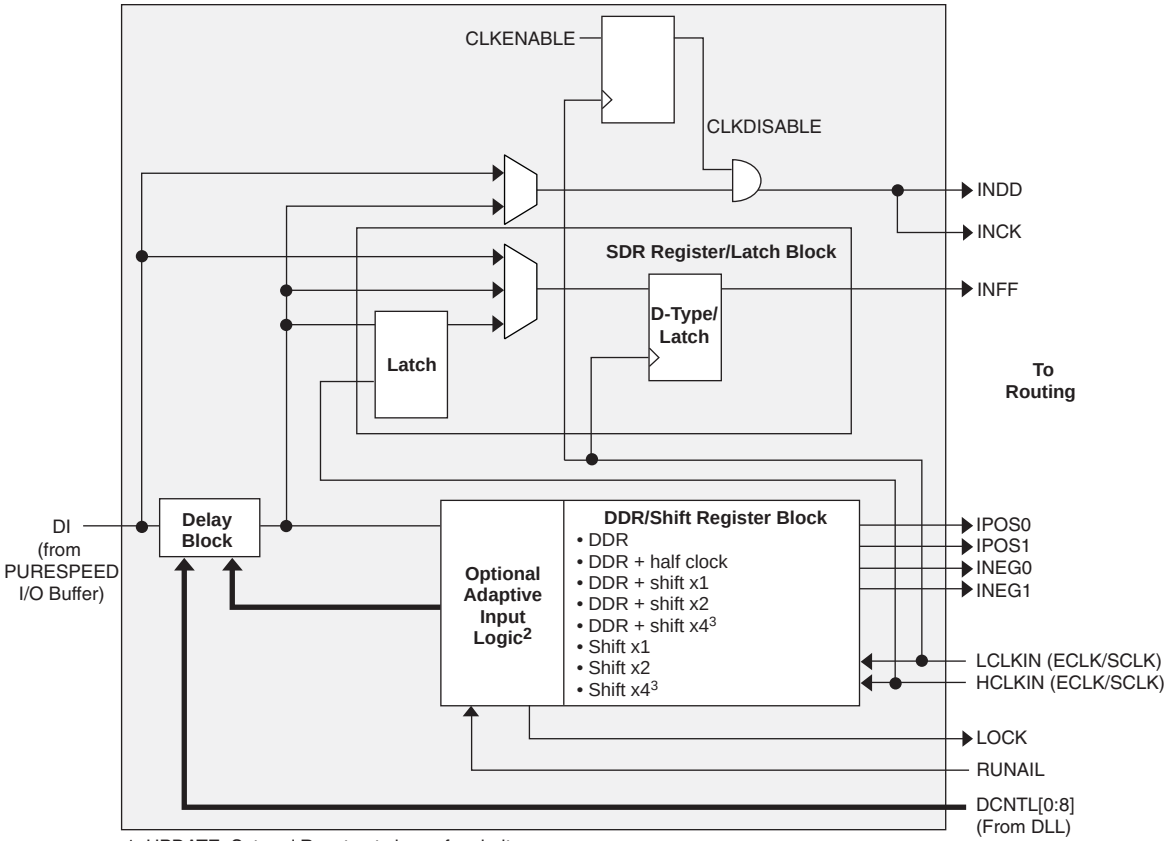


For further information on the DLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory Block

The sysMEM block can implement single port, true dual port, pseudo dual port or FIFO memories. Dedicated FIFO support logic allows the LatticeSC devices to efficiently implement FIFOs without consuming LUTs or routing resources for flag generation. Each block can be used in a variety of depths and widths as shown in Table 2-5. Memory with ranges from x1 to x18 in all modes: single port, pseudo-dual port and FIFO also providing x36.

Figure 2-20. Input Register Block[1]



1. UPDATE, Set and Reset not shown for clarity
2. Adaptive input logic is only available in selected PIO
3. By four shift modes utilize DDR/shift register block from paired PIO.
4. CLKDISABLE is used to block the transitions on the DQS pin during post-amble. Its main use is to disable DQS (typically found in DDR memory interfaces) or other clock signals. It can also be used to disable any/all input signals to save power.

flexiPCS quads are not dedicated solely to industry standard protocols. Each quad (and each channel within a quad) can be programmed for many user defined data manipulation modes. For example, modes governing user-defined word alignment and multi-channel alignment can be programmed for non-standard protocol applications.

For more information on the functions and use of the flexiPCS, refer to the LatticeSC/M Family flexiPCS Data Sheet.

System Bus

Each LatticeSC device connects the FPGA elements with a standardized bus framework referred to as a System Bus. Multiple bus masters optimize system performance by sharing resources between different bus masters such as the MPI and configuration logic. The wide data bus configuration of 32 bits with 4-bit parity supports high-bandwidth, data intensive applications.

There are two types of interfaces on the System Bus, master and slave. A master interface has the ability to perform actions on the bus, such as writes and reads to and from a specific address. A slave interface responds to the actions of a master by accepting data and address on a write and providing data on a read. The System Bus has a memory map which describes each of the slave peripherals that is connected on the bus. Using the addresses listed in the memory map, a master interface can access each of the slave peripherals on the System Bus. Any and all peripherals on the System Bus can be used at the same time. Table 2-12 list all of the available user peripherals on the System Bus after device power-up.

Table 2-12. System Bus User Peripherals

Peripheral	Name	Interface Type
Micro Processor Interface	MPI	Master
User Master Interface	UMI	Master
User Slave Interface	USI	Slave
Serial Management Interface (PLL, DLL, User Logic)	SMI	Slave
Physical Coding Sublayer	PCS	Slave
Direct FPGA Access	DFA	Slave

The peripherals listed in Table 2-12 can be added when the System Bus module is created using Module IP/Manager (ispLEVER Module/IP Manager).

Figure 2-31 also lists the existing peripherals on the System Bus. The gray boxes are available only during configuration. Refer to Lattice technical note TN1080, LatticeSC sysCONFIG Usage Guide, for configuration options. The Status and Config box refers to internal System Bus registers. This document presents all the interfaces listed in Table 2-12 in detail to help the user utilize the desired functions of the System Bus.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB10	VCC	-		VCC	-	
AB21	VCC	-		VCC	-	
J10	VCC	-		VCC	-	
J21	VCC	-		VCC	-	
K10	VCC	-		VCC	-	
K11	VCC	-		VCC	-	
K12	VCC	-		VCC	-	
K13	VCC	-		VCC	-	
K14	VCC	-		VCC	-	
K17	VCC	-		VCC	-	
K18	VCC	-		VCC	-	
K19	VCC	-		VCC	-	
K20	VCC	-		VCC	-	
K21	VCC	-		VCC	-	
K22	VCC	-		VCC	-	
K9	VCC	-		VCC	-	
L10	VCC	-		VCC	-	
L21	VCC	-		VCC	-	
M10	VCC	-		VCC	-	
M21	VCC	-		VCC	-	
N10	VCC	-		VCC	-	
N21	VCC	-		VCC	-	
P10	VCC	-		VCC	-	
P21	VCC	-		VCC	-	
U10	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
V10	VCC	-		VCC	-	
V21	VCC	-		VCC	-	
W10	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
Y10	VCC	-		VCC	-	
Y21	VCC	-		VCC	-	
H11	VCCAUX	-		VCCAUX	-	
H12	VCCAUX	-		VCCAUX	-	
H19	VCCAUX	-		VCCAUX	-	
H20	VCCAUX	-		VCCAUX	-	
M23	VCCAUX	-		VCCAUX	-	
M24	VCCAUX	-		VCCAUX	-	
N23	VCCAUX	-		VCCAUX	-	
N24	VCCAUX	-		VCCAUX	-	
U23	VCCAUX	-		VCCAUX	-	
U24	VCCAUX	-		VCCAUX	-	
V23	VCCAUX	-		VCCAUX	-	
V24	VCCAUX	-		VCCAUX	-	
W23	VCCAUX	-		VCCAUX	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E22	VCC12	-		VCC12	-	
E21	VCC12	-		VCC12	-	
E3	VCC12	-		VCC12	-	
E4	VCC12	-		VCC12	-	
E6	VCC12	-		VCC12	-	
E7	VCC12	-		VCC12	-	
E8	VCC12	-		VCC12	-	
E9	VCC12	-		VCC12	-	
E11	VCC12	-		VCC12	-	
E12	VCC12	-		VCC12	-	
A23	GND	-		GND	-	
A31	GND	-		GND	-	
AA13	GND	-		GND	-	
AA15	GND	-		GND	-	
AA18	GND	-		GND	-	
AA20	GND	-		GND	-	
AA26	GND	-		GND	-	
AA6	GND	-		GND	-	
AB10	GND	-		GND	-	
AB24	GND	-		GND	-	
AC14	GND	-		GND	-	
AC22	GND	-		GND	-	
AC29	GND	-		GND	-	
AC3	GND	-		GND	-	
AD11	GND	-		GND	-	
AD19	GND	-		GND	-	
AD27	GND	-		GND	-	
AD7	GND	-		GND	-	
AF12	GND	-		GND	-	
AF18	GND	-		GND	-	
AF24	GND	-		GND	-	
AF30	GND	-		GND	-	
AF4	GND	-		GND	-	
AG15	GND	-		GND	-	
AG21	GND	-		GND	-	
AG9	GND	-		GND	-	
AJ10	GND	-		GND	-	
AJ16	GND	-		GND	-	
AJ20	GND	-		GND	-	
AJ26	GND	-		GND	-	
AJ29	GND	-		GND	-	
AJ4	GND	-		GND	-	
AK13	GND	-		GND	-	
AK17	GND	-		GND	-	
AK23	GND	-		GND	-	
AK7	GND	-		GND	-	
AL1	GND	-		GND	-	
AL32	GND	-		GND	-	
AM2	GND	-		GND	-	
AM31	GND	-		GND	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C32	VCC12	-		VCC12	-	
E34	NC	-		PL22A	7	
F34	NC	-		PL22B	7	
F33	NC	-		PL24A	7	
G33	NC	-		PL24B	7	
K30	NC	-		PL25A	7	
L30	NC	-		PL25B	7	
G34	NC	-		PL26A	7	
H34	NC	-		PL26B	7	
M32	NC	-		PL39A	7	
N32	NC	-		PL39B	7	
P28	NC	-		PL39C	7	
R28	NC	-		PL39D	7	
J34	NC	-		PL41A	7	
K34	NC	-		PL41B	7	
P30	NC	-		PL41C	7	
R30	NC	-		PL41D	7	
W34	NC	-		PL59A	6	
Y34	NC	-		PL59B	6	
W32	NC	-		PL61A	6	
Y32	NC	-		PL61B	6	
AA34	NC	-		PL64A	6	
AB34	NC	-		PL64B	6	
AC34	NC	-		PL67A	6	
AD34	NC	-		PL67B	6	
Y30	NC	-		PL68A	6	
AA30	NC	-		PL68B	6	
AB33	NC	-		PL69A	6	
AC33	NC	-		PL69B	6	
AC2	NC	-		PR69B	3	
AB2	NC	-		PR69A	3	
AA5	NC	-		PR68B	3	
Y5	NC	-		PR68A	3	
AD1	NC	-		PR67B	3	
AC1	NC	-		PR67A	3	
AB1	NC	-		PR64B	3	
AA1	NC	-		PR64A	3	
Y3	NC	-		PR61B	3	
W3	NC	-		PR61A	3	
Y1	NC	-		PR59B	3	
W1	NC	-		PR59A	3	
R5	NC	-		PR41D	2	
P5	NC	-		PR41C	2	
K1	NC	-		PR41B	2	
J1	NC	-		PR41A	2	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
W30	PL69B	6	
W27	PL69C	6	VREF1_6
Y27	PL69D	6	
T33	PL70A	6	
U33	PL70B	6	
V25	PL70C	6	
W25	PL70D	6	
U34	PL71A	6	
V34	PL71B	6	
V26	PL71C	6	
W26	PL71D	6	
V33	PL74A	6	
W33	PL74B	6	
V24	PL74C	6	
W24	PL74D	6	
W31	PL77A	6	
Y31	PL77B	6	
Y29	PL77C	6	
AA29	PL77D	6	
Y33	PL79A	6	
AA33	PL79B	6	
Y28	PL79C	6	
AA28	PL79D	6	
AB32	PL90A	6	
AC32	PL90B	6	
AA26	PL90C	6	
AA27	PL90D	6	DIFFR_6
AB31	PL91A	6	
AC31	PL91B	6	
Y24	PL91C	6	
AA24	PL91D	6	
AE34	PL92A	6	
AF34	PL92B	6	
AB30	PL92C	6	
AC30	PL92D	6	
AD33	PL94A	6	
AE33	PL94B	6	
AD30	PL94C	6	
AE30	PL94D	6	
AE32	PL96A	6	
AF32	PL96B	6	
AA25	PL96C	6	
AB25	PL96D	6	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN8	PB123B	4	
AG11	PB123C	4	
AG10	PB123D	4	
AP7	PB125A	4	
AP6	PB125B	4	
AG13	PB125C	4	
AG12	PB125D	4	
AN7	PB127A	4	
AN6	PB127B	4	
AK9	PB127C	4	
AK8	PB127D	4	
AP5	PB129A	4	
AP4	PB129B	4	
AD11	PB129C	4	
AE11	PB129D	4	
AM7	PB131A	4	
AM6	PB131B	4	
AJ9	PB131C	4	
AJ8	PB131D	4	
AP3	PB133A	4	
AN3	PB133B	4	
AF10	PB133C	4	
AE10	PB133D	4	
AL7	PB135A	4	
AL6	PB135B	4	
AK7	PB135C	4	
AK6	PB135D	4	
AN5	PB138A	4	
AN4	PB138B	4	
AH9	PB138C	4	VREF1_4
AH8	PB138D	4	
AM3	PB139A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AM4	PB139B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AG9	PB139C	4	
AG8	PB139D	4	
AN2	PB141A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AM2	PB141B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AJ6	PB141C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AH6	PB141D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF7	PROBE_VCC	-	
AF8	PROBE_GND	-	
AG7	PR117D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AG6	PR117C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
U22	VCCAUX	-	
V13	VCCAUX	-	
V22	VCCAUX	-	
V23	VCCAUX	-	
W13	VCCAUX	-	
W22	VCCAUX	-	
Y21	GND	-	
Y25	GND	-	
C18	VCCIO1	-	
D17	VCCIO1	-	
F16	VCCIO1	-	
G19	VCCIO1	-	
J20	VCCIO1	-	
K12	VCCIO1	-	
K15	VCCIO1	-	
L23	VCCIO1	-	
Y9	GND	-	
J9	VCCIO1	-	
E3	VCCIO2	-	
G6	VCCIO2	-	
H4	VCCIO2	-	
K7	VCCIO2	-	
L3	VCCIO2	-	
M11	VCCIO2	-	
N6	VCCIO2	-	
P4	VCCIO2	-	
R9	VCCIO2	-	
AA3	VCCIO3	-	
AB7	VCCIO3	-	
AC10	VCCIO3	-	
AD4	VCCIO3	-	
AE6	VCCIO3	-	
AG3	VCCIO3	-	
AK4	VCCIO3	-	
T7	VCCIO3	-	
U3	VCCIO3	-	
V4	VCCIO3	-	
W6	VCCIO3	-	
Y10	VCCIO3	-	
AD12	VCCIO4	-	
AF15	VCCIO4	-	
AF9	VCCIO4	-	
AH10	VCCIO4	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W33	PL42C	7		PL56C	7	
Y33	PL42D	7		PL56D	7	
W37	PL43A	7		PL57A	7	
Y37	PL43B	7		PL57B	7	
Y32	PL43C	7		PL57C	7	
AA32	PL43D	7		PL57D	7	
U38	PL46A	7		PL60A	7	
V38	PL46B	7		PL60B	7	
W34	PL46C	7		PL60C	7	
Y34	PL46D	7		PL60D	7	
T40	PL47A	7	PCLKT7_1	PL61A	7	PCLKT7_1
U40	PL47B	7	PCLKC7_1	PL61B	7	PCLKC7_1
AA33	PL47C	7	PCLKT7_3	PL61C	7	PCLKT7_3
AB33	PL47D	7	PCLKC7_3	PL61D	7	PCLKC7_3
R42	PL48A	7	PCLKT7_0	PL62A	7	PCLKT7_0
T42	PL48B	7	PCLKC7_0	PL62B	7	PCLKC7_0
AA34	PL48C	7	PCLKT7_2	PL62C	7	PCLKT7_2
AB34	PL48D	7	PCLKC7_2	PL62D	7	PCLKC7_2
U41	PL50A	6	PCLKT6_0	PL64A	6	PCLKT6_0
V41	PL50B	6	PCLKC6_0	PL64B	6	PCLKC6_0
V36	PL50C	6	PCLKT6_1	PL64C	6	PCLKT6_1
W36	PL50D	6	PCLKC6_1	PL64D	6	PCLKC6_1
U42	PL51A	6		PL65A	6	
V42	PL51B	6		PL65B	6	
AB31	PL51C	6	PCLKT6_3	PL65C	6	PCLKT6_3
AC31	PL51D	6	PCLKC6_3	PL65D	6	PCLKC6_3
W38	PL52A	6		PL66A	6	
Y38	PL52B	6		PL66B	6	
AA35	PL52C	6	PCLKT6_2	PL66C	6	PCLKT6_2
AB35	PL52D	6	PCLKC6_2	PL66D	6	PCLKC6_2
W39	PL55A	6		PL69A	6	
Y39	PL55B	6		PL69B	6	
AB32	PL55C	6	VREF1_6	PL69C	6	VREF1_6
AC32	PL55D	6		PL69D	6	
W40	PL56A	6		PL70A	6	
Y40	PL56B	6		PL70B	6	
AA36	PL56C	6		PL70C	6	
AB36	PL56D	6		PL70D	6	
W41	PL57A	6		PL71A	6	
Y41	PL57B	6		PL71B	6	
AA37	PL57C	6		PL71C	6	
AB37	PL57D	6		PL71D	6	
W42	PL59A	6		PL73A	6	
Y42	PL59B	6		PL73B	6	
AC33	PL59C	6		PL73C	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C3	GND	-		GND	-	
C30	GND	-		GND	-	
C33	GND	-		GND	-	
C35	GND	-		GND	-	
C36	GND	-		GND	-	
C39	GND	-		GND	-	
C4	GND	-		GND	-	
C40	GND	-		GND	-	
C7	GND	-		GND	-	
C8	GND	-		GND	-	
D15	GND	-		GND	-	
D21	GND	-		GND	-	
D25	GND	-		GND	-	
D31	GND	-		GND	-	
F4	GND	-		GND	-	
F40	GND	-		GND	-	
G11	GND	-		GND	-	
G17	GND	-		GND	-	
G26	GND	-		GND	-	
G32	GND	-		GND	-	
H14	GND	-		GND	-	
H20	GND	-		GND	-	
H23	GND	-		GND	-	
H29	GND	-		GND	-	
H35	GND	-		GND	-	
H8	GND	-		GND	-	
J3	GND	-		GND	-	
J39	GND	-		GND	-	
L16	GND	-		GND	-	
L27	GND	-		GND	-	
L36	GND	-		GND	-	
L7	GND	-		GND	-	
M19	GND	-		GND	-	
M24	GND	-		GND	-	
M4	GND	-		GND	-	
M40	GND	-		GND	-	
N12	GND	-		GND	-	
N31	GND	-		GND	-	
P35	GND	-		GND	-	
P8	GND	-		GND	-	
R15	GND	-		GND	-	
R28	GND	-		GND	-	
R3	GND	-		GND	-	
R39	GND	-		GND	-	
T11	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AW25	VCCIO5	-		VCCIO5	-	
AW31	VCCIO5	-		VCCIO5	-	
AW37	VCCIO5	-		VCCIO5	-	
AY22	VCCIO5	-		VCCIO5	-	
AY28	VCCIO5	-		VCCIO5	-	
AY34	VCCIO5	-		VCCIO5	-	
AB39	VCCIO6	-		VCCIO6	-	
AC36	VCCIO6	-		VCCIO6	-	
AD32	VCCIO6	-		VCCIO6	-	
AE40	VCCIO6	-		VCCIO6	-	
AF35	VCCIO6	-		VCCIO6	-	
AG31	VCCIO6	-		VCCIO6	-	
AH39	VCCIO6	-		VCCIO6	-	
AJ36	VCCIO6	-		VCCIO6	-	
AK32	VCCIO6	-		VCCIO6	-	
AL40	VCCIO6	-		VCCIO6	-	
AM35	VCCIO6	-		VCCIO6	-	
AP39	VCCIO6	-		VCCIO6	-	
AR36	VCCIO6	-		VCCIO6	-	
AU40	VCCIO6	-		VCCIO6	-	
AA40	VCCIO7	-		VCCIO7	-	
H36	VCCIO7	-		VCCIO7	-	
J40	VCCIO7	-		VCCIO7	-	
L35	VCCIO7	-		VCCIO7	-	
M39	VCCIO7	-		VCCIO7	-	
P36	VCCIO7	-		VCCIO7	-	
R40	VCCIO7	-		VCCIO7	-	
T31	VCCIO7	-		VCCIO7	-	
U35	VCCIO7	-		VCCIO7	-	
V39	VCCIO7	-		VCCIO7	-	
W32	VCCIO7	-		VCCIO7	-	
Y36	VCCIO7	-		VCCIO7	-	
AA14	VTT_2	2		VTT_2	2	
AA15	VTT_2	2		VTT_2	2	
R12	VTT_2	2		VTT_2	2	
V14	VTT_2	2		VTT_2	2	
AB14	VTT_3	3		VTT_3	3	
AB15	VTT_3	3		VTT_3	3	
AE14	VTT_3	3		VTT_3	3	
AJ13	VTT_3	3		VTT_3	3	
AH21	VTT_4	4		VTT_4	4	
AJ18	VTT_4	4		VTT_4	4	
AJ19	VTT_4	4		VTT_4	4	
AJ20	VTT_4	4		VTT_4	4	
AJ21	VTT_4	4		VTT_4	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH22	VTT_5	5		VTT_5	5	
AJ22	VTT_5	5		VTT_5	5	
AJ23	VTT_5	5		VTT_5	5	
AJ24	VTT_5	5		VTT_5	5	
AJ25	VTT_5	5		VTT_5	5	
AB28	VTT_6	6		VTT_6	6	
AB29	VTT_6	6		VTT_6	6	
AE29	VTT_6	6		VTT_6	6	
AJ30	VTT_6	6		VTT_6	6	
AA28	VTT_7	7		VTT_7	7	
AA29	VTT_7	7		VTT_7	7	
R31	VTT_7	7		VTT_7	7	
V29	VTT_7	7		VTT_7	7	
Y24	GND	-		GND	-	
Y26	GND	-		GND	-	
Y8	GND	-		GND	-	
Y35	GND	-		GND	-	
AA16	VCC12	-		VCC12	-	
AA27	VCC12	-		VCC12	-	
AB16	VCC12	-		VCC12	-	
AB27	VCC12	-		VCC12	-	
AF16	VCC12	-		VCC12	-	
AF27	VCC12	-		VCC12	-	
AG17	VCC12	-		VCC12	-	
AG21	VCC12	-		VCC12	-	
G33	NC	-		NC	-	
G10	NC	-		NC	-	
M15	NC	-		NC	-	
L15	NC	-		NC	-	
K16	NC	-		NC	-	
J16	NC	-		NC	-	
M18	NC	-		NC	-	
L18	NC	-		NC	-	
M25	NC	-		NC	-	
L25	NC	-		NC	-	
J27	NC	-		NC	-	
K27	NC	-		NC	-	
L28	NC	-		NC	-	
M28	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M80 and LatticeSC/M115 in a 1704-pin package supports a 32-bit MPI interface.

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1101 - Power Estimation and Management for LatticeSC Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeSC/M Family Data Sheet Supplemental Information

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For Further Information

For further information about the flexiPCS, see the LatticeSC/M Family flexiPCS Data Sheet.

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- LatticeSC PURESPEED I/O Usage Guide (TN1088)
- LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide (TN1158)
- LatticeSC sysCLOCK PLL/DLL User's Guide (TN1098)
- On-Chip Memory Usage Guide for LatticeSC Devices (TN1094)
- LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide (TN1099)
- LatticeSC QDRII/II+ SRAM Memory Interface User's Guide (TN1096)
- LatticeSC sysCONFIG Usage Guide (TN1080)
- LatticeSC MPI/System Bus (TN1085)
- SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices (TN1100)
- Power Estimation and Management for LatticeSC Devices (TN1101)
- LatticeSC SERDES Jitter (TN1084)
- LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks (TN1110)
- Lattice PCI Express Basic Demo User's Guide (UG08)
- LatticeSC flexiPCS/SERDES Design Guide (TN1145)
- Temperature Sensing Diode in LatticeSC Devices (TN1115)
- SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: ww.pcisig.com

Date	Version	Section	Change Summary
June 2006 (cont.)	01.2 (cont.)	DC and Switching Characteristics (cont.)	Updated Typical Building Block Performance with ispLEVER 6.0 values.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 values.
			Updated Lattice SC Internal Timing Parameters with ispLEVER 6.0 values.
			Updated Lattice SC Family Timing Adders with ispLEVER 6.0 values
			Changed % spread from 1 to 0.5 min and from 3 to 1.5 max.
			Changed conditions to refer to “with multiplication” and “without multiplication”.
			Changed the formula for t_{OPJIT} with multiplication (same result, different representation).
		Pinout Information	Expanded definition of NC.
			Expanded definition of GND.
			Expanded definition of VTT_x.
			Expanded definition of VCC12.
			Added accuracy of TEMP pin.
			Added RESPN_[ULC/URC].
			Updated Pin Information Summary with additional devices and packages.
			Added additional devices and packages pinouts.
			Removed Power Supply and NC connections table
			Removed VTT table
			Removed LFSC25 Logic Signal Connections: 900-Ball ffBGA1 table
			Changed all VDDP, VDDTX and VDDRX to VCC12.
		Ordering Information	Added dual marking.
			Added lead free packaging information to part number description.
August 2006	01.3	Introduction	Added SC40 1152 information to Table 1-1.
			Updated Table 1-3 with ispLEVER 6.0 SP1 results.
		Architecture	Added SSTL18 II to Table 2-8.
			Changed Table 2-10 VCCIO column to “N/A” for LVDS, mini-LVDS, BLVDS25, MLVDS25, HYPT and RSDS.
			Changed Hypertransport performance to 700 MHz (1400 Mbps) in Table 2-11.
			Changed SPI4.2 performance to 500 MHz (1000 Mbps) in Table 2-11
			Added “On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.”
			Added VCCIO of 2.5 V for LVPECL33 in table 2-9.
		DC and Switching Characteristics	Updated Typical Building Block Performance with ispLEVER 6.0 SP1 results.
			Updated Initialization and Standby Supply Current table to break out ICC and ICC12.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 SP1 results.
			Updated LatticeSC Internal Timing Parameters with ispLEVER 6.0 SP1 results.

Date	Version	Section	Change Summary
August 2006 (cont.)	01.3 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Family Timing Adders with ispLEVER 6.0 SP1 results
			Updated PLL Timing Parameters based on PDE testing results
			Removed RDDATA parameter from sysCONFIG readback timing table
		Multiple	Changed TDO/RDDATA to TDO
		Pinout Information	Removed all MPI signals from SC15 256 pin package Dual Function Column
			Added note to SC15, SC25 900 pin package that the package supports a 16 bit MPI
			Added note that pin D3 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note that pin D28 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note to SC25 1020 pin package that the package supports a 16 bit MPI
			Added note to SC80 1152 pin package that the package supports a 32 bit MPI
			Added note to SC80 1704 pin package that the package supports a 32 bit MPI
		Ordering Information	Changed “fcBGA” for the 1020 packages to “ffBGA”
November 2006	01.4	Introduction	LatticeSC Family Selection Guide table – I/O count for SC80 device, 1704 fcBGA package changed to 904/32. I/O count for SC115 device, 1704 fcBGA package changed to 942/32.
		DC and Switching Characteristics	DC Electrical Characteristics table – Updated the initialization and standby supply current values.
			DC Electrical Characteristics table – Updated the sysCONFIG Master Parallel mode RCLK low and RCLK high time specifications.
			DC Electrical Characteristics table – Updated VCCIO values for LVPECL33 I/Os.
		Pin Information	Pin Information Summary table - Changed number of single ended user I/Os from 906 to 904 for 1704 fcBGA.
			Removed the single-ended only output restriction on pins D3 and D28 in an SC15 and SC25 900 pin package.
		Ordering Information	Ordering Information tables - Changed number of I/Os from 906 to 904 for 1704 fcBGA.
			Added ordering part numbers for LatticeSC/SCM 40K and 115K LUT devices.
			Added lead-free ordering part numbers.
		Multiple	Changed number of available SC80 I/O from 906 to 904.
			Changed number of available SC115 I/O from 944 to 942.
January 2007	01.4a	Architecture	Added EBR Asynchronous Reset section.
February 2007	01.4b	Architecture	Updated EBR Asynchronous Reset section.
March 2007	01.5	Architecture	Added EBR asynchronous reset clarification
			Clarified that differential drivers are not supported in banks 1, 4 and 5
		DC and Switching Characteristics	Added clarification for the description of the junction temperature specification in the Absolute Maximum Ratings section.
			Updated Initialization and Standby Current table.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.1 SP1 results.